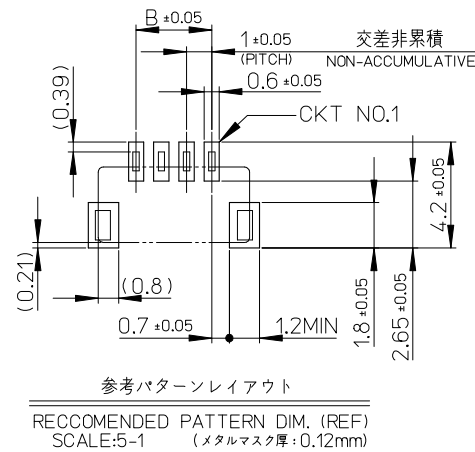
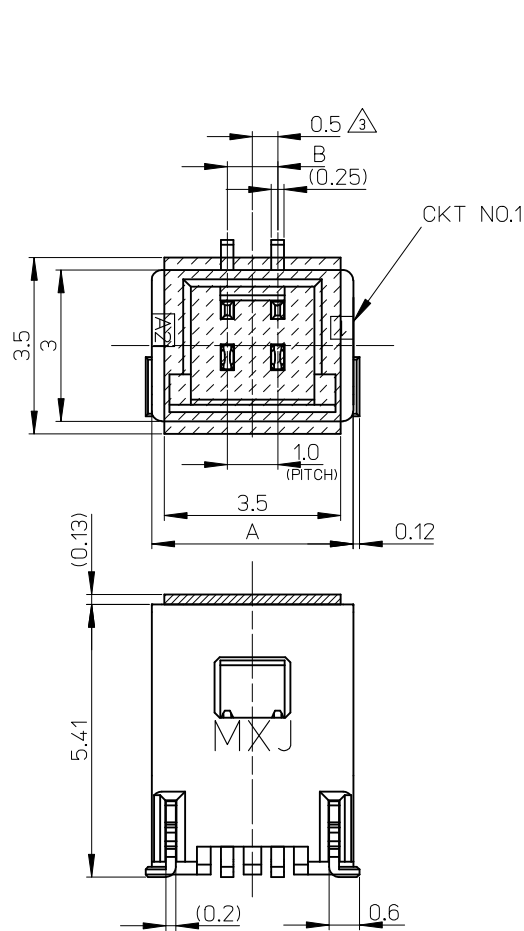




番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	ポリアミド UL94V-0 色:自然色 POLYAMIDE, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 部分金メッキ:0.1μmMIN. SEPARATED GOLD PLATING ニッケルメッキ(下地):1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ:1.0μmMIN. TIN ニッケルメッキ(下地):1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

- 嵌合相手: 501330-****
MATE WITH: 501330-****
- ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
- 6~15極については、SD-504449-002を参照下さい。
REFER TO SD-504449-002 ABOUT 6-15CKT.
- ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

4.0	7.0	504449-0507	5
3.0	6.0	504449-0407	4
2.0	5.0	504449-0307	3
1.0	4.0	504449-0207	2
B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT.

※対応可能な極数は、別途お問い合わせ下さい。

RELEASED EC NO: J2012-1436 DRWN: KWASHIO CHKD: KASAKAWA APPR: YOITO REV: 0	DESCRIPTION 2012/12/13 2012/12/14 2012/12/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION					
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 2-5CKT							
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE								
		30 OVER	± 0.3	APPROVED BY	DATE	molex							
		ANGULAR ±3 °		MATERIAL NO.	DOCUMENT NO.						SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE							SD-50449-001		
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

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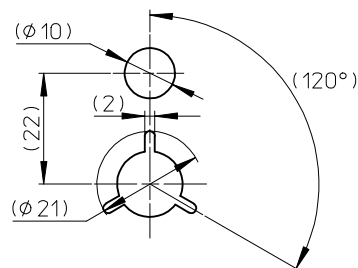
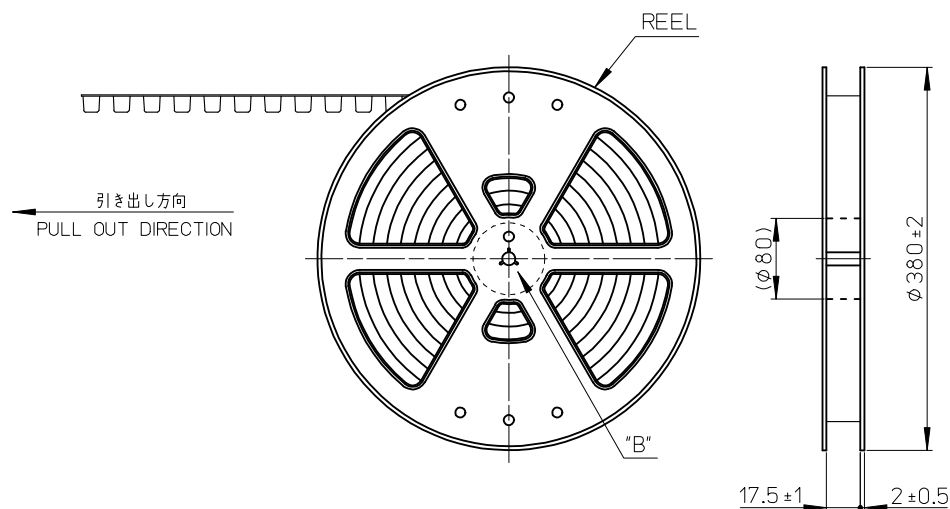
C

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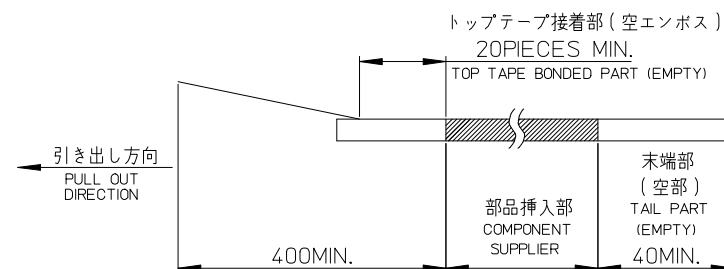
A



DETAIL "B"

NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量: 1100個/リール
NUMBER OF CONNECTORS: 1100PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET、PE、REF
TOP TAPE
リール: ポリスチレン<リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
(504449-0607~1507以外)
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.
(BESIDES 504449-0607~1507)

RELEASED EC NO: J2012-1436 2012/12/13 DRWN: KWASHIO 2012/12/14 CHKD: KASAKAWA APPR: YOITO 2012/12/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY KWASHIO	DATE 2012/12/13	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG			
		10 OVER 30 UNDER	±0.25	CHECKED BY	DATE				
		30 OVER	±0.3	APPROVED BY YOITO	DATE 2012/12/21				
		ANGULAR ±1 °		MATERIAL NO.					DOCUMENT NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2		SD-504449-003				1 OF 2
0	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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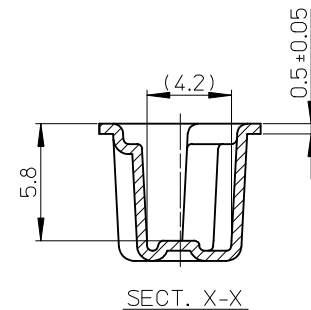
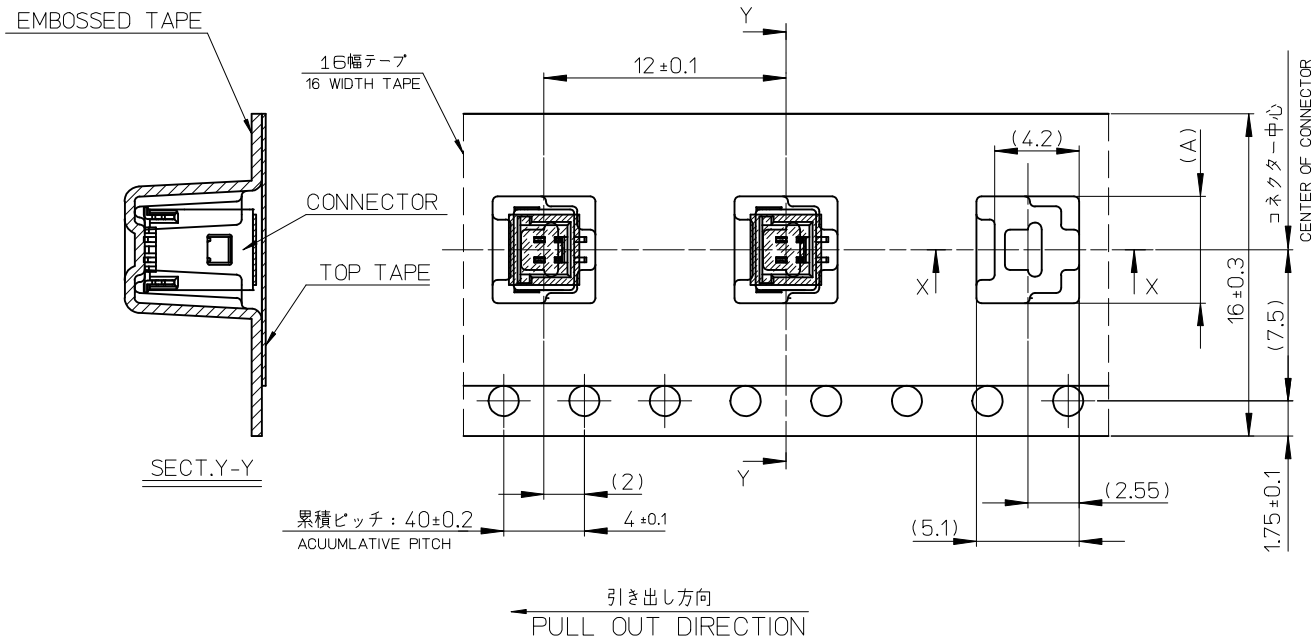
5

4

3

2

10 9 8 7 6 5 4 3 2 1



8.3	504449-0507	5
7.3	504449-0407	4
6.3	504449-0307	3
5.3	504449-0207	2
(A)	EMBOSSSED PACKAGE	CKT.
	オーダー番号 ORDER NO.	

CONNECTOR SERIES NO. 504449-***9

SCALE --- DESIGN UNITS METRIC THIRD ANGLE PROJECTION

TITLE 1.0 WIRE TO BOARD CONN.
WAFER ASS'Y (1-ROW S/T)
EMBSTP PKG

molex

DOCUMENT NO. SD-504449-003 SHEET NO. 2 OF 2

SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SEE SHEET1	EC NO.: J2012-1436 DRAWN: KWASHIO CHKD: KASAKAWA APPR: YOI TO	2012/12/13 2012/12/14 2012/12/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	
				10 UNDER	± 0.2
				10 OVER 30 UNDER	± 0.25
				30 OVER	± 0.3
				ANGULAR ±1 °	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
REV					

SEE SHEET1
EC NO: J2012-1436
DRWN: KWASHIO
CHKD: KASAKAWA
APPR: YOITO

9 8 7 6 5 4 3 2